



深圳市泰河电子有限公司

SHENZHEN TH ELECTRONICS CO;LTD

产品确认书

Product Confirmation

CUSTOMER: _____

Product :

声表面谐振器

Frequency:

R315M

Model:

F-11 DIP

DATE: _____

承认后请寄回一份

PLS SEND BACK ONE COPY TO US AFTER YOUR APPROVAL

承认结果 CONCLUSION	客户签名 SIGNATURE	客户承认章 STAMP	日期 DATE	备注 REMARK
合格 ACCEPT				
不合格 REJECT				

制表: 刘小姐 _____

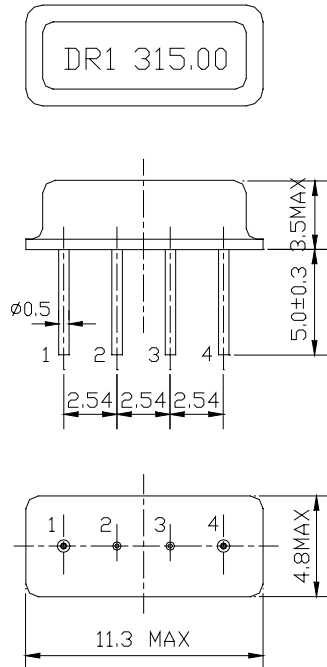
审核: _____
(公章)

尊敬的客户: 请您抽出一点时间, 在7-10个工作日内将承认书回签, 若未回签, 以视默认. 谢谢合作!

TH R315M 声表面谐振器F-11 DIP

1. Package Dimension (F-11)

Unit: mm



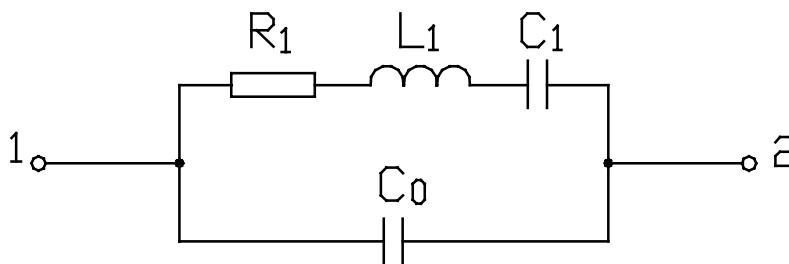
Pin No.	Function
1.	Input
2.	Ground
3.	Ground
4.	Output

2. Marking

TH 315.00

1. Color: Black or Blue
2. DR: Manufacture's logo
3. 1: One-port SAW Resonator
4. 315.00: Center Frequency (MHz)

3. Equivalent LC Model



TH R315M 声表面谐振器F-11 DIP

4. Performance

4.1 Maximum Rating

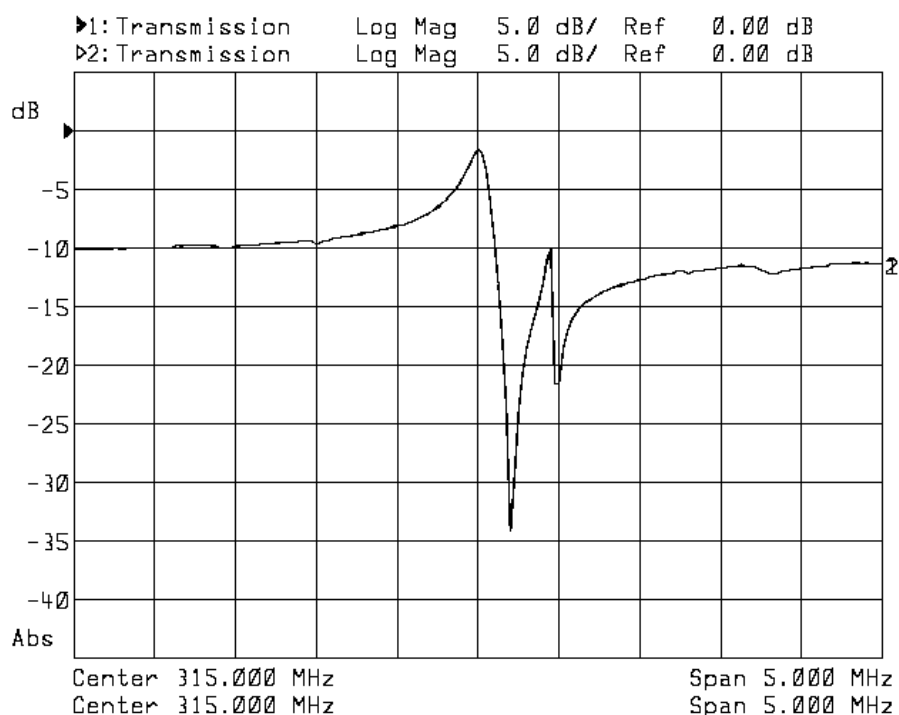
DC Voltage V_{DC}	10V
AC Voltage V_{PP}	10V (50Hz/60Hz)
Operation Temperature	-40 to +85
Storage Temperature	-45 to +85
RF Power Dissipation	0dBm

4.2 Electronic Characteristics

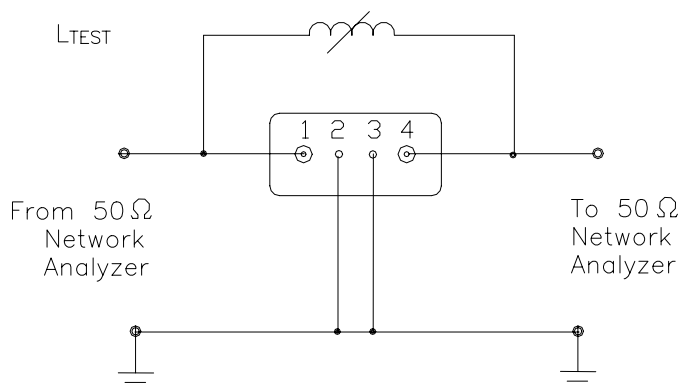
Item		Units	Minimum	Typical	Maximum
Center Frequency f_o		MHz	314.925	315	315.075
Insertion Loss		dB	—	1.3	2.5
Quality Factor	Unloaded Q	—	—	12,000	—
	50 Loaded Q	—	—	1,900	—
Temperature	Turnover Temperature		10	25	40
Stability	Turnover Frequency	KHz	—	f_o	—
	Freq.Temp.Coefficient	ppm/°C	—	0.037	—
Frequency Aging		ppm/yr	—	$< \pm 10$	—
DC Insulation Resistance		M	1.0	—	—
RF Equivalent RLC Model	Motional Resistance R_1		—	23	29
	Motional Inductance L_1	μH	—	115.2	—
	Motional Capacitance C_1	fF	—	2.2	—
	Shunt Static Capacitance C_0	pF	2.1	2.4	2.7

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4.3 Frequency Characteristics



4.4 Test Circuit



Note: Reference temperature shall be 25 ± 2 . However, the measurement may be carried out at 5 to 35 unless there is a dispute.

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5. Reliability

5.1 Mechanical Shock: The components shall remain within the electrical specifications after 1000 shocks, acceleration 392 m/s^2 , duration 6 milliseconds.

5.2 Vibration Fatigue: The components shall remain within the electrical specifications after loaded vibration at 20 Hz, amplitude 1.5 mm, for 2 hours.

5.3 Terminal Strength: The components shall remain within the electrical specifications after pulled 2 kgs weight for 10 seconds towards an axis of each terminal.

5.4 High Temperature Storage: The components shall remain within the electrical specifications after being kept at the 85 ± 2 for 48 hours, then kept at room temperature for 2 hours.

5.5 Low Temperature Storage: The components shall remain within the electrical specifications after being kept at the -25 ± 2 for 48 hours, then kept at room temperature for 2 hours.

5.6 Temperature Cycle: The components shall remain within the electrical specifications after 5 cycles of high and low temperature testing (one cycle: 80 for 30 minutes 25 for 5 minutes -25 for 30 minutes)than kept at room temperature for 2 hours.

5.7 Solder-heat Resistance: The components shall remain within the electrical specifications after dipped in the solder at 260 for 10 ± 1 seconds, then kept at room temperature for 2 hours. (Terminal must be dipped leaving 1.5 mm from the case).

5.8 Solderability: Solderability of terminal shall be kept at more than 80% after dipped in the solder flux at 230 ± 5 for 5 ± 1 seconds.

6. Remarks

6.1 Static voltage

Static voltage between signal load & ground may cause deterioration & destruction of the component. Please avoid static voltage.

6.2 Ultrasonic cleaning

Ultrasonic vibration may cause deterioration & destruction of the component. Please avoid ultrasonic cleaning.

6.3 Soldering

Only leads of component may be soldered. Please avoid soldering another part of component.